## **Amended Claims**

1

- 1. (withdrawn) A LVTSCR-like structure having one or more diodes formed in a p-well of the structure.
- 2. (currently amended) A method of increasing the holding voltage of an LVTSCR structure, comprising

that includes forming an n-well and a p-well formed in a substrate,

a gate, forming a first n+ region and a first p+ region formed in the n-well to define an anode a high voltage node on one side of the gate, and

forming a second n+ region and a second p+ region formed in the p-well to define a cathode.

providing a gate between the anode and the cathode, and

low voltage node on the other side of the gate, the method comprising forming an additional n+ region inside the p-well of the structure to define a p-n junction of a diode between the additional n+ region and the p-well, with the second p+ region forming a contact to the diode, and and, the p-n junction being forward biased during normal operation by having said additional n+ region of the p-n junction located further from the high voltage node than the second p+ region, wherein the diode is located between the anode and the cathode.

3. (currently amended) A method of increasing the holding voltage of an LVTSCR structure comprising

forming having an anode in an n-well and a cathode in a p-well, the cathode being defined by an n+ region and a p+ region, comprising forming at least one additional n+ region and at least one additional p+

region in the p-well to define at least one forward biased diode under normal operation in the p-well, the at least one forward biased diode being located between the anode and the cathode, thereby providing an alternative current path from anode to cathode through said at least one <u>forward biased</u> diode.

- 4. (currently amended) A method of claim 3, wherein the alternative current path defines a lower resistance current path than the current path defined by the p-well.
- 5. (canceled)

J

4

- 6. (canceled)
- 7. (canceled)
- 8. (canceled)
- 9. (currently amended) A method of claim 2, further comprising forming at least one additional p+ region and multiple additional n+ regions inside the p-well of the structure to define multiple diodes each with a p-n junction in the p-well, each diode being formed by between a p-type material and an n-type material, wherein the p-type material is defined by the p-well having one of the additional p+ regions or the second p+ region as diode contact, and wherein the n-type material is defined by one of the additional n+ regions.